



Material Content Data Sheet



Sales Product Name		TLE8110EE		Issued		27. September 2017		
MA#		MA001120902						
Package		PG-DSO-36-51		Weight*		610.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.468	2.53	2.53	25329	25329
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		372	
	non noble metal	iron	7439-89-6	4.546	0.74		7444	
wire	non noble metal	copper	7440-50-8	184.568	30.22	31.01	302238	310147
	non noble metal	copper	7440-50-8	2.370	0.39	0.39	3882	3882
	encapsulation	organic material	carbon black	1333-86-4	0.786	0.13		1288
encapsulation	plastics	epoxy resin	-	36.168	5.92		59227	
	inorganic material	silicondioxide	60676-86-0	356.177	58.33	64.38	583258	643773
leadfinish	non noble metal	tin	7440-31-5	5.440	0.89	0.89	8909	8909
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1295	1295
glue	plastics	epoxy resin	-	1.018	0.17		1666	
	noble metal	silver	7440-22-4	3.053	0.50	0.67	4999	6665
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com